

DESCRIPTION

TITLE OF INVENTION: SUBSTRATE, SELECTIVE FILM DEPOSITION
METHOD, DEPOSITION FILM OF ORGANIC MATTER, AND ORGANIC
5 MATTER

TECHNICAL FIELD

[0001]

The present disclosure relates to a substrate, a
10 selective film deposition method of selectively depositing
a film in a surface region containing a metal element on a
substrate, an organic substance deposited film, an organic
substance, etc.

BACKGROUND ART

15 [0002]

As recent semiconductor chips have increasingly
miniaturized structures, problems such as many steps and
high cost exist in conventional lithography in which
20 patterning is carried out by selectively removing a portion
of a structure. If chemical vapor deposition (CVD) or
atomic layer deposition (ALD) can be used to form a film
selectively in a desired region on a substrate, this is
considered to be an optimal process for forming a
25 microstructure and solve the above problems.

[0003]

However, when CVD or ALD is used to selectively
deposit a film on a substrate including multiple surface
regions of different materials such as metals used in
30 electrodes or wirings and inorganic dielectrics used in
insulating films, a film for inhibiting deposition needs to
be selectively deposited, but the conventional methods do
not have sufficiently high selectivity.

[0004]

35 A known selective film formation method includes

depositing a material for inhibiting film deposition in a region where film formation is not desired. Patent Literature 1, for example, discloses a method for forming a thin film pattern of an inorganic material such as TiN, AlN, or SiN on a substrate by atomic layer deposition (ALD), which includes: forming a pattern of an atomic layer deposition-inhibiting layer on a substrate by screen printing or the like using an atomic layer deposition-inhibiting material including a fluoro-resin having a fluorine content of 30 atom% or higher, containing at least one tertiary or quaternary carbon atom, and not containing ester, hydroxyl, carboxyl, or imide groups; and then forming an inorganic material layer by atomic layer deposition in a region where the atomic layer deposition-inhibiting layer is not present.

[0005]

Moreover, Patent Literature 2 discloses a method for selectively depositing a layer on a substrate including an exposed metal surface and an exposed silicon-containing surface, which includes: (a) growing a first self-assembled monolayer on the exposed metal surface; (b) growing an organosilane-based second self-assembled monolayer on the exposed silicon-containing surface; (c) heating the substrate to remove the first self-assembled monolayer from the exposed metal surface; (d) depositing a low-k dielectric layer or a metal layer selectively on the exposed metal surface; and (e) heating the substrate to remove the second self-assembled monolayer from the exposed silicon-containing surface.

[0006]

The above method can be applied to a substrate including first and second surfaces of different materials to deposit a film on the first surface selectively over the second surface by using the difference in surface state between the two surfaces. The above method can also reduce

the number of steps involved in a process for forming a microstructure.

[0007]

Moreover, Patent Literature 3, for example, discloses
5 a process which includes subjecting a substrate including a first surface that is a metallic surface and a second surface that is a dielectric surface to a deposition cycle including a step of bringing the substrate into contact with a first gas phase precursor and a step of bringing the
10 substrate into contact with a second gas phase precursor, thereby forming an organic thin film on the first surface selectively over the second surface. It is described in Example 1 of Patent Literature 3 that a 200 mm silicon wafer including tungsten (W) features alternating with
15 silicon oxide surfaces as a substrate was subjected to 250 to 1000 cycles of deposition using 1,6-diaminohexane (DAH) and pyromellitic dianhydride (PMDA) to form a polyimide film, and the polyimide film on the metallic tungsten surface was thicker than the polyimide film on the SiO₂
20 surface.

[0008]

Patent Literature 4 discloses a method that uses the selective deposition of an organic film described in Patent Literature 3 to form a passivation layer selectively on a
25 first surface made of a metal, followed by forming a layer X only on a second surface of a dielectric, and also discloses a method that uses the above method to form a metallization structure of an integrated circuit.

30 CITATION LIST

- Patent Literature

[0009]

Patent Literature 1: WO2016/147941 A1

Patent Literature 2: JP 2018-512504 A

35 Patent Literature 3: JP 2017-216448 A

Patent Literature 4: JP 2018-137435 A

SUMMARY OF INVENTION

- Technical Problem

5 [0010]

However, Patent Literature 1, in which a predetermined pattern is formed on a substrate of a single material using an atomic layer deposition-inhibiting material, does not disclose a method of forming an atomic layer deposition-inhibiting layer selectively on a desired surface region on a substrate including multiple surface regions of different materials.

[0011]

The organosilane-based self-assembled monolayer used in Patent Literature 2 can be deposited selectively on a silicon-containing surface but cannot be deposited selectively on a metal or metal oxide.

[0012]

The methods of selectively forming an organic thin film described in Patent Literature 3 and Patent Literature 4 involve repeating multiple times a deposition cycle including shifting raw materials and temperatures, and thus require considerable time and effort to form an organic thin film.

25 [0013]

In light of the above problems, the present disclosure aims to provide a selective film deposition method which can deposit a film of an organic substance on a surface region containing a metal element selectively over a surface region containing a nonmetal inorganic material on a substrate by a simple procedure, as well as an organic substance deposited film deposited by the method, the organic substance, etc.

35 - Solution to Problem

[0014]

As a result of extensive studies, the present inventors have found that the use of at least one organic substance represented by the formula (1) described below allows a film of the organic substance to be deposited on a surface region containing a metal element selectively over a surface region containing a nonmetal inorganic material on a substrate. This finding has led to the completion of the present invention.

10 [0015]

A selective film deposition method according to embodiments of the present disclosure includes exposing a substrate having a structure on which a first surface region containing a metal element and a second surface region containing a nonmetal inorganic material are both exposed, to a solution containing an organic substance represented by formula (1) shown below and a solvent to deposit a film of the organic substance on the first surface region selectively over the second surface region:

20 $R^1(X)_m$ (1)

wherein R^1 is a C4-C100 hydrocarbon group optionally containing a heteroatom or a halogen atom, and m hydrogen atoms of the hydrocarbon group are replaced with X; X is $-PO_3(R^2)_2$, $-O-PO_3(R^2)_2$, $-CO_2R^2$, $-SR^2$, or $-SSR^1$; each R^2 is a hydrogen atom or a C1-C6 alkyl group; and m is a positive integer, and m/r is 0.01 to 0.25 where r is the number of carbons of the hydrocarbon group.

[0016]

According to the specified selective film deposition method, it is possible with the use of the organic substance of formula (1) to provide a method which can deposit a film of an organic substance on a first surface region containing a metal element exposed on a substrate selectively over a second surface region containing a nonmetal inorganic material exposed on the substrate by a

simple procedure. Herein, a film made of an organic substance is also referred to as a film of an organic substance or an organic substance deposited film.

[0017]

5 A substrate according to embodiments of the present disclosure is a substrate including a first surface region containing a metal element and a second surface region containing a nonmetal inorganic material, wherein the first surface region includes a film of the organic substance of
10 formula (1), and the second surface region includes no film of the organic substance or a film of the organic substance on the second surface region has a thickness t_2 smaller than a thickness t_1 of the film of the organic substance on the first surface region.

15 [0018]

 According to the specified substrate, it is possible to provide a substrate on which a film of the organic substance is deposited on a first surface region containing a metal element selectively over a second surface region
20 containing a nonmetal inorganic material.

[0019]

 An organic substance deposited film according to embodiments of the present disclosure is an organic substance deposited film formed by the specified selective
25 film deposition method, wherein the deposited film includes the organic substance of formula (1) deposited on a substrate.

[0020]

 An organic substance according to embodiments of the present disclosure is the organic substance of formula (1)
30 for use in the specified selective film deposition method.

[0021]

 With the use of the specified organic substance, it is possible to deposit a film of an organic substance on a
35 first surface region containing a metal element exposed on

a substrate selectively over a second surface region containing a nonmetal inorganic material exposed on the substrate by a simple procedure.

[0022]

5 A solution according to embodiments of the present disclosure is a solution for use in the specified selective film deposition method, wherein the solution contains the organic substance of formula (1) and a solvent.

[0023]

10 With the use of the specified solution, it is possible to deposit a film of the organic substance on a first surface region containing a metal element exposed on a substrate selectively over a second surface region containing a nonmetal inorganic material exposed on the
15 substrate by a simple procedure.

- Advantageous Effects of Invention

[0024]

20 According to the selective film deposition method according to embodiments of the present disclosure, it is possible with the use of the organic substance of formula (1) to provide a method which can deposit a film of the organic substance on a first surface region containing a metal element exposed on a substrate selectively over a
25 second surface region containing a nonmetal inorganic material exposed on the substrate by a simple procedure.

[0025]

30 According to the substrate according to embodiments of the present disclosure, it is possible to provide a substrate on which a film of the organic substance of formula (1) is deposited on a first surface region containing a metal element exposed on the substrate selectively over a second surface region containing a nonmetal inorganic material exposed on the substrate.

35

DESCRIPTION OF EMBODIMENTS

[0026]

The present disclosure is described in detail below. The following description of structural elements provides
5 exemplary embodiments of the present disclosure. The present disclosure is not limited to such specific contents. Various modifications can be made within the scope of the gist.

[0027]

10 A selective film deposition method according to embodiments of the present disclosure includes exposing a substrate having a structure on which a first surface region containing a metal element and a second surface region containing a nonmetal inorganic material are both
15 exposed, to a solution containing an organic substance represented by the formula (1) shown below and a solvent to deposit a film of the organic substance on the first surface region selectively over the second surface region:
$$R^1(X)_m \quad (1)$$

20 wherein R^1 is a C4-C100 hydrocarbon group optionally containing a heteroatom or a halogen atom, and m hydrogen atoms of the hydrocarbon group are replaced with X; X is - $PO_3(R^2)_2$, -O- $PO_3(R^2)_2$, -CO₂R², -SR², or -SSR¹; each R^2 is a hydrogen atom or a C1-C6 alkyl group; and m is a positive
25 integer, and m/r is 0.01 to 0.25 where r is the number of carbons of the hydrocarbon group.

[0028]

According to the specified selective film deposition method, it is possible with the use of the organic
30 substance of formula (1) to deposit a film of an organic substance on a first surface region containing a metal element exposed on a substrate selectively over a second surface region containing a nonmetal inorganic material exposed on the substrate by a simple procedure.

35 [0029]

Here, the expression "deposit a film of the organic substance on the first surface region selectively over the second surface region" means that the film of the organic substance is deposited on the first surface region, and the film of the organic substance is not deposited on the second surface region or the thickness of the film of the organic substance on the first surface region is greater than the thickness of the film of the organic substance on the second surface region.

Whether the film of the organic substance is deposited or not can be determined by dropping pure water mainly on the surface of the substrate and measuring the angle (contact angle) between the water droplet and the substrate surface by a contact angle meter.

[0030]

When the organic substance of formula (1) has a poor affinity with water, the contact angle with water increases on a substrate surface on which a film of the organic substance is deposited. In the selective film deposition method according to embodiments of the present disclosure, the contact angle with water is preferably higher in the first surface region than in the second surface region. Specifically, the contact angle with water is preferably higher by at least 10° , more preferably at least 20° , still more preferably at least 30° in the first surface region than in the second surface region.

Thus, it can be determined that a film of the organic substance is deposited on the first surface region with a higher contact angle with water selectively over the second surface region with a lower contact angle with water.

In the present disclosure, the contact angle with water in the first surface region is preferably 80° or more, more preferably 90° or more, still more preferably 100° or more. In contrast, the contact angle with water in the second surface region to which no or only a slight

organic substance is attached is preferably about 20 to 70°.

[0031]

Whether the organic substance deposited film is
5 formed on the substrate or not can also be determined by
analyzing the elemental composition on the substrate
surface by x-ray photoelectron spectroscopy (XPS). When
the organic substance contains a characteristic atom such
as phosphorus or sulfur, the peak of that element can be
10 observed.

[0032]

The easiness of deposition of the organic substance
on the first surface region and the second surface region
varies depending on the material of the surface regions.
15 Preferably, the thickness t_1 of the film of the organic
substance on the first surface region is greater than the
thickness t_2 of the film of the organic substance on the
second surface region, and the value obtained by dividing
 t_1 by t_2 , i.e., t_1/t_2 , is 5 or greater. Further, the value
20 of t_1/t_2 is more preferably 10 or greater, still more
preferably 100 or greater. Moreover, the film thickness t_1
is preferably 0.3 nm or more, more preferably 0.6 nm or
more, while t_2 is preferably less than 0.3 nm, more
preferably 0 nm, i.e., no organic substance is deposited.
25 The thicknesses t_1 and t_2 can be measured by an atomic
force microscope (AFM), for example.

[0033]

The metal element may be at least one metal element
selected from the group consisting of Cu, Co, Ru, Ni, Pt,
30 Al, Ta, Ti, and Hf. The metal element may be present in
the form of a metal or a compound containing a metal
element. The compound containing a metal element may be
any compound chemically bound to the metal element, such as
a metal oxide, a metal nitride, or an alloy. A metal or a
35 metal oxide is particularly preferred. The metal element

is also preferably Cu, Co, or Ru.

[0034]

Examples of the nonmetal inorganic material include silicon-based materials such as silicon, silicon oxide, silicon nitride, and silicon oxynitride, and germanium-based materials such as germanium, germanium oxide, germanium nitride, and germanium oxynitride. Among these, the nonmetal inorganic material is preferably at least one selected from the group consisting of silicon, silicon oxide, silicon nitride, and silicon oxynitride. The term "silicon" includes both polycrystalline silicon and monocrystalline silicon. The silicon oxide is represented by the chemical formula: SiO_x where x is at least 1 but not more than 2, such as typically SiO_2 . Moreover, the silicon nitride is represented by the chemical formula: SiN_x where x is at least 0.3 but not more than 9, such as typically Si_3N_4 . The silicon oxynitride is represented by $\text{Si}_4\text{O}_x\text{N}_y$ where x is at least 3 but not more than 6, and y is at least 2 but not more than 4, such as $\text{Si}_4\text{O}_5\text{N}_3$.

[0035]

The first surface region on which a metal is exposed may be prepared, for example, by producing a metal film using chemical vapor deposition (CVD), physical vapor deposition (PVD), plating, or other techniques. For example, a substrate having a structure on which a first surface region containing a metal and a second surface region containing a nonmetal inorganic material are both exposed may be prepared by forming a metal film on a film of a nonmetal inorganic material as described above and forming the metal film into a predetermined pattern by photolithography; or by forming a hole or groove on a film of the nonmetal inorganic material and filling the groove with a metal, optionally followed by chemical mechanical polishing (CMP).

The first surface region on which a metal is exposed

may also be prepared by eliminating an oxide film from the surface of a metal film by vapor phase etching or wet etching to expose the metal surface. The oxide film may be mechanically eliminated.

5 [0036]

The first surface region in which a metal oxide is exposed may be prepared, for example, by producing a metal oxide film by chemical vapor deposition (CVD), physical vapor deposition (PVD), or other techniques; or by exposing
10 a metal film produced as above to the air to form a natural oxide film. For example, a substrate having a structure on which a first surface region containing a metal oxide and a second surface region containing a nonmetal inorganic material are both exposed may be prepared by forming a
15 metal oxide film on a film of a nonmetal inorganic material as described above and forming the metal oxide film into a predetermined pattern by photolithography; or by forming a hole or groove on a film of the nonmetal inorganic material, filling the groove with a metal, and forming a
20 natural oxide film on the metal.

[0037]

The first surface region containing a metal element may contain another component other than the compound containing a metal element on which the organic substance
25 of formula (1) can be deposited. However, desirably, the first surface region contains only the compound containing a metal element, and only the compound containing a metal element is exposed on the surface.

The second surface region containing a nonmetal
30 inorganic material may contain a compound of the nonmetal inorganic material or may contain only the nonmetal inorganic material. However, desirably, the second surface region contains only the nonmetal inorganic material, and only the nonmetal inorganic material is exposed on the
35 surface.

[0038]

Examples of the substrate used in embodiments of the present disclosure include a semiconductor device substrate including a metal or metal oxide film in its structure, and
 5 a substrate on which a metal or a metal oxide is formed during a semiconductor device patterning step.

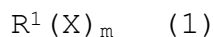
Particularly preferred is a substrate in which a predetermined pattern of a metal wiring is formed on a semiconductor element insulating film. In other words, the
 10 first surface region corresponds to a metal wiring including a surface natural oxide film or a metal wiring on which a metal is exposed, and the second surface region corresponds to an insulating film made of a nonmetal inorganic material. However, the substrate used in
 15 embodiments of the present disclosure is not limited thereto.

[0039]

Specifically, a film of the organic substance of formula (1) is deposited on the first surface region
 20 selectively over the second surface region using a method of exposing the substrate to a solution containing the organic substance and a solvent. This method is described below.

[0040]

25 The organic substance to be used is an organic substance represented by the following formula (1):



wherein R^1 is a C4-C100 hydrocarbon group optionally containing a heteroatom or a halogen atom, and m hydrogen
 30 atoms of the hydrocarbon group are replaced with X; X is - $PO_3(R^2)_2$, -O- $PO_3(R^2)_2$, - CO_2R^2 , - SR^2 , or - SSR^1 ; each R^2 is a hydrogen atom or a C1-C6 alkyl group; and m is a positive integer, and m/r is 0.01 to 0.25 where r is the number of carbons of the hydrocarbon group.

35 [0041]

Conceptually, the term "organic substance of formula (1)" encompasses organic substances represented by formulas (2) to (5), and may be, for example, at least one organic substance represented by at least one selected from the group consisting of formulas (2) to (5).
[0042]

The organic substances of formulas (2) to (5) are described below.

[Organic substance of formula (2) (including organic substance of formula (6))]

In formula (2) $[R^3(PO_3(R^4)_2)_n]$, R^3 is a C4-C100 hydrocarbon group optionally containing a heteroatom or a halogen atom, and n hydrogen atoms of the hydrocarbon group are replaced with $(PO_3(R^4)_2)$; n is 1 or 2; and R^4 is a hydrogen atom or a C1-C6 alkyl group.

R^4 is preferably a hydrogen atom. When R^4 is a hydrogen atom, the organic substance is a phosphonic acid. Here, each R^4 may be the same or different.
[0043]

Further, the organic substance of formula (2) $[R^3(PO_3(R^4)_2)_n]$ is preferably an organic substance represented by formula (6) $[R^{11}-PO_3H_2]$. In formula (6), R^{11} is a C6-C100 monovalent hydrocarbon group optionally containing a heteroatom or a halogen atom.

[0044]

[Organic substance of formula (3) (including organic substance of formula (7))]

In formula (3) $[R^5(O-PO_3(R^6)_2)_n]$, R^5 is a C4-C100 hydrocarbon group optionally containing a heteroatom or a halogen atom, and n hydrogen atoms of the hydrocarbon group are replaced with $(O-PO_3(R^6)_2)$; n is 1 or 2; and R^6 is a hydrogen atom or a C1-C6 alkyl group.

R^6 is preferably a hydrogen atom. When R^6 is a hydrogen atom, the organic substance is a phosphate ester. Here, each R^6 may be the same or different.

[0045]

Further, the organic substance of formula (3) $[R^5(O-PO_3(R^6)_2)_n]$ is preferably an organic substance represented by formula (7) $[R^{12}-O-PO_3H_2]$. In formula (7), R^{12} is a C6-
 5 C100 monovalent hydrocarbon group optionally containing a heteroatom or a halogen atom.

[0046]

[Compound of formula (4) (including compound of formula (8))]

10 In formula (4) $[R^7(CO_2R^8)_n]$, R^7 is a C4-C100 hydrocarbon group optionally containing a heteroatom or a halogen atom, and n hydrogen atoms of the hydrocarbon group are replaced with (CO_2R^8) ; n is 1 or 2; and R^8 is a hydrogen atom or a C1-C6 alkyl group.

15 R^8 is preferably a hydrogen atom. When R^8 is a hydrogen atom, the organic substance is a carboxylic acid. Here, each R^8 may be the same or different.

[0047]

Further, the organic substance of formula (4)
 20 $[R^7(CO_2R^8)_n]$ is preferably an organic substance represented by formula (8) $[R^{13}-CO_2H]$. In formula (8), R^{13} is a C6-C100 monovalent hydrocarbon group optionally containing a heteroatom or a halogen atom.

[0048]

25 [Organic substance of formula (5) (including organic substance of formula (9))]

In formula (5) $[R^9(SR^{10})_n]$, R^9 is a C4-C100 hydrocarbon group optionally containing a heteroatom or a halogen atom, and n hydrogen atoms of the hydrocarbon group
 30 are replaced with (SR^{10}) ; n is 1 or 2; and R^{10} is a hydrogen atom, a C1-C6 alkyl group, or $-S-R^9$.

R^{10} is preferably a hydrogen atom. When R^{10} is a hydrogen atom, the organic substance is a thiol. Here, each R^{10} may be the same or different.

35 [0049]

Further, the organic substance of formula (5) $[R^9(SR^{10})_n]$ is preferably an organic substance represented by formula (9) $[R^{14}-SH]$. In formula (9), R^{14} is a C6-C100 monovalent hydrocarbon group optionally containing a

5 heteroatom or a halogen atom.
[0050]

Examples of the heteroatoms optionally contained in the hydrocarbon groups of R^3 , R^5 , R^7 , R^9 , R^{11} , R^{12} , R^{13} , and R^{14} include nitrogen, oxygen, sulfur, and phosphorus atoms.

10 Examples of the halogen atoms include fluorine, chlorine, bromine, and iodine atoms.

[0051]

Moreover, R^3 , R^5 , R^7 , R^9 , R^{11} , R^{12} , R^{13} , and R^{14} may each include a branched structure or a cyclic structure. The

15 branched structure contains a secondary or tertiary carbon atom at which the chain is branched. Moreover, examples of the cyclic structure include alicyclic hydrocarbons and aryl groups. Examples of the alicyclic hydrocarbons include cyclopentyl, cyclohexyl, adamantyl, norbornyl, and

20 camphoryl groups. Examples of the aryl groups include phenyl, o-tolyl, m-tolyl, p-tolyl, p-hydroxyphenyl, 1-naphthyl, 1-anthracenyl, and benzyl groups.

[0052]

Examples of the organic substance of formula (2) or

25 (6) include methylphosphonic acid, ethylphosphonic acid, n-propylphosphonic acid, n-butylphosphonic acid, n-pentylphosphonic acid, n-hexylphosphonic acid, n-heptylphosphonic acid, n-octylphosphonic acid, n-nonylphosphonic acid, n-decylphosphonic acid, n-

30 undecylphosphonic acid, n-dodecylphosphonic acid, n-tridecylphosphonic acid, n-tetradecylphosphonic acid, n-pentadecylphosphonic acid, n-hexadecylphosphonic acid, n-heptadecylphosphonic acid, n-octadecylphosphonic acid, n-nonadecylphosphonic acid, phenylphosphonic acid, (2-

35 phenylethyl)phosphonic acid, (3-phenylpropyl)phosphonic

acid, (4-phenylbutyl)phosphonic acid, (5-phenylpentyl)phosphonic acid, (6-phenylhexyl)phosphonic acid, (7-phenylhexyl)phosphonic acid, (8-phenyloctyl)phosphonic acid, (9-phenylnonyl)phosphonic acid, (10-phenyldecyl)phosphonic acid, (11-phenylundecyl)phosphonic acid, (12-phenyldodecyl)phosphonic acid, methylenediphosphonic acid, (4-aminophenyl)phosphonic acid, (4-aminobenzyl)phosphonic acid, benzhydrylphosphonic acid, (4-bromophenyl)phosphonic acid, (2-chloroethyl)phosphonic acid, (3-chloropropyl)phosphonic acid, (4-chlorobutyl)phosphonic acid, (5-chloropentyl)phosphonic acid, (6-chlorohexyl)phosphonic acid, (2-bromoethyl)phosphonic acid, (3-bromopropyl)phosphonic acid, (4-bromobutyl)phosphonic acid, (5-bromopentyl)phosphonic acid, (6-bromohexyl)phosphonic acid, 1,2-ethylenediphosphonic acid, 1,3-propylenediphosphonic acid, 1,4-butanediphosphonic acid, 1,5-pentanediphosphonic acid, 1,6-hexylenediphosphonic acid, alendronic acid, 1,4-phenylenediphosphonic acid, o-xylylenediphosphonic acid, m-xylylenediphosphonic acid, p-xylylenediphosphonic acid, (aminomethyl)phosphonic acid, (1-aminoethyl)phosphonic acid, 2-(perfluorobutyl)ethylphosphonic acid, 2-(perfluorohexyl)ethylphosphonic acid, and 2-(perfluoroheptyl)ethylphosphonic acid.

[0053]

Examples of the organic substance of formula (3) or (7) include those in which the phosphonyl group ($-\text{PO}_3\text{H}$ group) of the exemplary phosphonic acids listed above is replaced with $-\text{OPO}_3\text{H}$. Examples include n-hexyl phosphate, n-heptyl phosphate, n-octyl phosphate, n-nonyl phosphate, n-decyl phosphate, n-undecyl phosphate, n-dodecyl phosphate, n-tridecyl phosphate, n-tetradecyl phosphate, n-pentadecyl phosphate, n-hexadecyl phosphate, n-heptadecyl phosphate, n-octadecyl phosphate, n-nonadecyl phosphate,

phenyl phosphate, benzyl dihydrogen phosphate, 2-phenylethylphosphoric acid, 3-phenylpropylphosphoric acid, 4-phenylbutylphosphoric acid, 5-phenylpentylphosphoric acid, 6-phenylhexylphosphoric acid, 7-phenylheptylphosphoric acid, 8-phenyloctylphosphoric acid, 9-phenylnonylphosphoric acid, 10-phenyldecylphosphoric acid, 11-phenylundecylphosphoric acid, 12-phenyldodecylphosphoric acid, diethyl phosphate, dipropyl phosphate, dibutyl phosphate, dipentyl phosphate, dihexyl phosphate, diheptyl phosphate, dioctyl phosphate, dinonyl phosphate, didecyl phosphate, phenyl phosphate, diphenyl phosphate, dibenzyl phosphate, 2-(perfluorobutyl)ethylphosphoric acid, 2-(perfluoropentyl)ethylphosphoric acid, 2-(perfluorohexyl)ethylphosphoric acid, and 2-(perfluoroheptyl)ethylphosphoric acid.

[0054]

Examples of the organic substance of formula (4) or (8) include those in which the phosphonyl group ($-\text{PO}_3\text{H}$ group) of the exemplary phosphonic acids listed above is replaced with $-\text{CO}_2\text{H}$. Examples include n-hexanoic acid, n-heptanoic acid, n-octanoic acid, n-nonanoic acid, n-decanoic acid, n-undecanoic acid, n-dodecanoic acid, n-tridecanoic acid, n-tetradecanoic acid, n-pentadecanoic acid, n-hexadecanoic acid, n-heptadecanoic acid, n-octadecanoic acid, n-nonadecanoic acid, benzoic acid, 2-phenylethanoic acid, 3-phenylpropanoic acid, 4-phenylbutanoic acid, 5-phenylpentanoic acid, 6-phenylhexanoic acid, 7-phenylheptanoic acid, 8-phenyloctanoic acid, 9-phenylnonanoic acid, 10-phenyldecanoic acid, 11-phenylundecanoic acid, 12-phenyldodecanoic acid, 1,2-ethanedicarboxylic acid, 1,3-propanedicarboxylic acid, 1,4-butanedicarboxylic acid, 1,5-pentanedicarboxylic acid, 1,6-hexanedicarboxylic acid, 1,7-heptanedicarboxylic acid, 1,8-octanedicarboxylic acid, 1,9-

nonanedicarboxylic acid, 1,10-decanedicarboxylic acid,
 1,11-undecanedicarboxylic acid, 1,12-dodecanedicarboxylic
 acid, 1,13-tridecanedicarboxylic acid, 1,14-
 tetradecanedicarboxylic acid, 1,15-pentadecanedicarboxylic
 5 acid, 1,16-hexadecanedicarboxylic acid, 1,17-
 heptadecanedicarboxylic acid, 1,2-cyclohexanedicarboxylic
 acid, 1,4-cyclohexanedicarboxylic acid, 1,3-
 cyclohexanedicarboxylic acid, diethylmalonic acid,
 dipropylmalonic acid, dibutylmalonic acid, dipentylmalonic
 10 acid, dihexylmalonic acid, o-phthalic acid, m-phthalic
 acid, p-phthalic acid, 2-(perfluorobutyl)ethanoic acid, 2-
 (perfluoropentyl)ethanoic acid, 2-(perfluorohexyl)ethanoic
 acid, 2-(perfluoroheptyl)ethanoic acid, 2-
 (perfluorohexyl)propanoic acid, perfluoro-1,4-butanedioic
 15 acid, perfluoro-1,5-pentanedioic acid, perfluoro-1,6-
 hexanedioic acid, perfluoro-1,7-heptanedioic acid,
 perfluoro-1,8-octanedioic acid, 4,4'-bisbenzoic acid, and
 4,4'-(hexafluoroisopropylidene)bis(benzoic acid).
 [0055]

20 Examples of the organic substance of formula (5) or
 (9) include those in which the phosphonyl group ($-\text{PO}_3\text{H}$
 group) of the exemplary phosphonic acids listed above is
 replaced with $-\text{SH}$. Examples include n-hexanethiol, n-
 heptanethiol, n-octanethiol, n-nonanethiol, n-decanethiol,
 25 n-undecanethiol, n-dodecanethiol, n-tridecanethiol, n-
 tetradecanethiol, n-pentadecanethiol, n-hexadecanethiol, n-
 heptadecanethiol, n-octadecanethiol, n-nonadecanethiol,
 cyclohexanethiol, thiophenol, phenylmethanethiol, 2-
 phenylethanethiol, 3-phenylpropanethiol, 4-
 30 phenylbutanethiol, 5-phenylpentanethiol, 6-
 phenylhexanethiol, 7-phenylheptanethiol, 8-
 phenyloctanethiol, 9-phenylnonanethiol, 10-
 phenyldecylthiol, 11-phenylundecylthiol, 12-
 phenyldodecylthiol, ethanedithiol, 1,3-propanedithiol, 1,4-
 35 butanedithiol, 1,5-pentanedithiol, 1,6-hexanedithiol, 1,7-

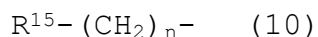
heptanedithiol, 1,8-octanedithiol, 1,9-nonanedithiol, 1,10-decanedithiol, 1,11-undecanedithiol, 1,12-dodecanedithiol, 1,13-tridecanedithiol, 1,14-tetradecanedithiol, 1,15-pentadecanedithiol, 1,16-hexadecanedithiol, 1,17-heptadecanedithiol, 1,18-octadecanedithiol, 1,19-nonadecanedithiol, 1,2-benzenedithiol, 1,3-benzenedithiol, 1,4-benzenedithiol, 1,4-benzenedimethanethiol, 2-(perfluorobutyl)ethanethiol, 2-(perfluoropentyl)ethanethiol, 2-(perfluorohexyl)ethanethiol, and 2-(perfluoroheptyl)ethanethiol.

[0056]

The hydrogen atoms in each of R^1 , R^3 , R^5 , R^7 , R^9 , R^{11} , R^{12} , R^{13} , and R^{14} are preferably partially or fully replaced with fluorine atoms because the heat resistance can be improved. In particular, the hydrogen atoms are preferably replaced with a plurality of fluorine atoms. More preferably, a perfluoroalkyl group is present.

[0057]

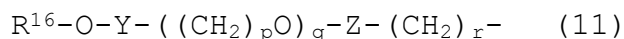
Moreover, to increase the amount of the organic substance deposited, R^{11} , R^{12} , R^{13} , and R^{14} are each preferably a monovalent organic group represented by the following formula (10):



wherein R^{15} is a hydrogen atom or a monovalent hydrocarbon group optionally containing a heteroatom or a halogen atom; and n is an integer of 2 to 20, and the total number of carbons in formula (10) is 6 to 100.

[0058]

Again, to increase the amount of the organic substance deposited, R^{11} , R^{12} , R^{13} , and R^{14} are each preferably a monovalent organic group represented by the following formula (11):



wherein R^{16} is a hydrogen atom, a methyl group, or a phenyl

group; Y and Z are each any divalent group or a direct bond; p is an integer of 1 to 4, and q and r are positive integers; the total number of carbons in formula (11) is 6 to 100; and the repeating units $(\text{CH}_2)_p\text{O}$ and CH_2 may be
5 present in any order in the formula.

Further, formula (11) is preferably $\text{R}^{16}\text{-O-}((\text{CH}_2)_p\text{O})_q\text{-}(\text{CH}_2)_r\text{-}$, and the total number of carbons in formula (11) is preferably 10 to 90, more preferably 20 to 80.

[0059]

10 Moreover, to increase the amount of the organic substance deposited, R^1 , R^3 , R^5 , R^7 , R^9 , R^{11} , R^{12} , R^{13} , and R^{14} are each preferably a linear hydrocarbon group not containing a branched structure. The linear hydrocarbon group may contain a cyclic structure. The cyclic structure
15 is preferably an aryl group, particularly a phenyl group, and is preferably present at the tip of the linear hydrocarbon group.

[0060]

In the selective film deposition method according to
20 embodiments of the present disclosure, the substrate is exposed to a solution containing the organic substance of formula (1) and a solvent to deposit a film of the organic substance on the first surface region selectively over the second surface region.

25 The phrase "the substrate is exposed to the solution" means bringing the surface of the substrate into contact with the solution.

[0061]

A specific example of the selective film deposition
30 method may include immersing a substrate including a first surface region and a second surface region in a solution containing the organic substance of formula (1) and a solvent to bring the solution into contact with the surface of the substrate and deposit a film of the organic
35 substance selectively on the first surface region of the

substrate. The above method is referred to as the immersion method.

[0062]

In addition to the immersion method in which the substrate is immersed in the solution, the substrate may be exposed to the solution by a method such as a spin coating method in which the solution is dropped onto the substrate and the substrate is then rotated at a high speed; a spray coating method in which the solution is sprayed to the substrate; or an application method in which the solution is applied to the substrate. The method is not limited to these methods as long as it can bring the substrate into contact with the solution.

[0063]

The concentration of the organic substance of formula (1) in the solution is preferably at least 0.01 mass% but not more than 20 mass%, more preferably at least 0.05 mass% but not more than 10 mass%, still more preferably at least 0.1 mass% but not more than 8 mass%, particularly preferably at least 0.3 mass% but not more than 5 mass%, based on 100 mass% of the total amount of the solution. When the solution contains two or more such organic substances, the concentration range indicated above means the total concentration of these organic substances.

[0064]

The solvent used in the solution of the present disclosure may be any conventionally known solvent that can dissolve the above-described organic substance and that causes little damage to the surface of the workpiece. In order to be able to dissolve the organic substance and to cause little damage to the surface of the workpiece, the solvent preferably includes an organic solvent (nonaqueous solvent) excluding water. In view of the solubility of the organic substance, the solvent preferably includes an organic solvent (nonaqueous solvent) other than

hydrocarbon-based solvents.

[0065]

Suitable examples of the nonaqueous solvent other than hydrocarbon-based solvents include esters, ethers, ketones, sulfoxide-based solvents, sulfone-based solvents, lactone-based solvents, carbonate-based solvents, alcohol-based solvents, polyhydric alcohol derivatives, nitrogen element-containing solvents, silicone solvents, and mixtures thereof.

10 [0066]

Examples of the esters include ethyl acetate, n-propyl acetate, i-propyl acetate, n-butyl acetate, i-butyl acetate, n-pentyl acetate, i-pentyl acetate, n-hexyl acetate, n-heptyl acetate, n-octyl acetate, n-pentyl formate, n-butyl propionate, ethyl butyrate, n-propyl butyrate, i-propyl butyrate, n-butyl butyrate, methyl n-octanoate, methyl decanoate, methyl pyruvate, ethyl pyruvate, n-propyl pyruvate, methyl acetoacetate, ethyl acetoacetate, ethyl 2-oxobutanoate, dimethyl adipate, methyl 3-methoxypropionate, ethyl 3-methoxypropionate, methyl 3-ethoxypropionate, ethyl 3-ethoxypropionate, and ethyl ethoxyacetate.

[0067]

Examples of the ethers include di-n-propyl ether, ethyl-n-butyl ether, di-n-butyl ether, ethyl-n-amyl ether, di-n-amyl ether, ethyl-n-hexyl ether, di-n-hexyl ether, di-n-octyl ether, ethers containing a branched hydrocarbon group corresponding to the number of carbons of any of the foregoing ethers (such as diisopropyl ether and diisoamyl ether), dimethyl ether, diethyl ether, methyl ethyl ether, methyl cyclopentyl ether, diphenyl ether, tetrahydrofuran, dioxane, methyl perfluoropropyl ether, methyl perfluorobutyl ether, ethyl perfluorobutyl ether, methyl perfluorohexyl ether, and ethyl perfluorohexyl ether.

35 [0068]

Examples of the ketones include acetone, acetylacetone, methyl ethyl ketone, methyl propyl ketone, methyl butyl ketone, 2-heptanone, 3-heptanone, cyclohexanone, and isophorone.

5 [0069]

Examples of the sulfoxide-based solvents include dimethyl sulfoxide. Examples of the sulfone-based solvents include dimethyl sulfone, diethyl sulfone, bis(2-hydroxyethyl)sulfone, and tetramethylene sulfone.

10 [0070]

Examples of the lactone-based solvents include β -propiolactone, γ -butyrolactone, γ -valerolactone, γ -hexanolactone, γ -heptanolactone, γ -octanolactone, γ -nonanolactone, γ -decanolactone, γ -undecanolactone, γ -dodecanolactone, δ -valerolactone, δ -hexanolactone, δ -octanolactone, δ -nonanolactone, δ -decanolactone, δ -undecanolactone, δ -dodecanolactone, and ϵ -hexanolactone.
[0071]

Examples of the carbonate-based solvents include dimethyl carbonate, ethyl methyl carbonate, diethyl carbonate, and propylene carbonate. Examples of the alcohol-based solvents include methanol, ethanol, propanol, butanol, pentanol, hexanol, heptanol, octanol, ethylene glycol, diethylene glycol, 1,3-propanediol, 1,2-propanediol, dipropylene glycol, 1,2-butanediol, 1,3-butanediol, 1,4-butanediol, triethylene glycol, tripropylene glycol, tetraethylene glycol, tetrapropylene glycol, and glycerol.
[0072]

30 Examples of the polyhydric alcohol derivatives include OH-group containing polyhydric alcohol derivatives such as ethylene glycol monomethyl ether, ethylene glycol monoethyl ether, ethylene glycol monopropyl ether, ethylene glycol monobutyl ether, diethylene glycol monomethyl ether, diethylene glycol monoethyl ether, diethylene glycol

35

monopropyl ether, diethylene glycol monobutyl ether,
triethylene glycol monomethyl ether, triethylene glycol
monoethyl ether, triethylene glycol monopropyl ether,
triethylene glycol monobutyl ether, tetraethylene glycol
5 monomethyl ether, tetraethylene glycol monoethyl ether,
tetraethylene glycol monopropyl ether, tetraethylene glycol
monobutyl ether, propylene glycol monomethyl ether,
propylene glycol monoethyl ether, propylene glycol
monopropyl ether, propylene glycol monobutyl ether,
10 dipropylene glycol monomethyl ether, dipropylene glycol
monoethyl ether, dipropylene glycol monopropyl ether,
dipropylene glycol monobutyl ether, tripropylene glycol
monomethyl ether, tripropylene glycol monoethyl ether,
tripropylene glycol monopropyl ether, tripropylene glycol
15 monobutyl ether, tetrapropylene glycol monomethyl ether,
and butylene glycol monomethyl ether; and OH group-free
polyhydric alcohol derivatives such as ethylene glycol
dimethyl ether, ethylene glycol diethyl ether, ethylene
glycol dibutyl ether, ethylene glycol monomethyl ether
20 acetate, ethylene glycol monoethyl ether acetate, ethylene
glycol monobutyl ether acetate, ethylene glycol diacetate,
diethylene glycol dimethyl ether, diethylene glycol ethyl
methyl ether, diethylene glycol diethyl ether, diethylene
glycol butyl methyl ether, diethylene glycol dibutyl ether,
25 diethylene glycol monomethyl ether acetate, diethylene
glycol monoethyl ether acetate, diethylene glycol monobutyl
ether acetate, diethylene glycol diacetate, triethylene
glycol dimethyl ether, triethylene glycol diethyl ether,
triethylene glycol dibutyl ether, triethylene glycol butyl
30 methyl ether, triethylene glycol monomethyl ether acetate,
triethylene glycol monoethyl ether acetate, triethylene
glycol monobutyl ether acetate, triethylene glycol
diacetate, tetraethylene glycol dimethyl ether,
tetraethylene glycol diethyl ether, tetraethylene glycol
35 dibutyl ether, tetraethylene glycol monomethyl ether

acetate, tetraethylene glycol monoethyl ether acetate, tetraethylene glycol monobutyl ether acetate, tetraethylene glycol diacetate, propylene glycol dimethyl ether, propylene glycol diethyl ether, propylene glycol dibutyl ether, propylene glycol monomethyl ether acetate (propylene glycol 1-monomethyl ether 2-acetate), propylene glycol monoethyl ether acetate, propylene glycol monobutyl ether acetate, propylene glycol diacetate, dipropylene glycol dimethyl ether, dipropylene glycol methyl propyl ether, dipropylene glycol diethyl ether, dipropylene glycol dibutyl ether, dipropylene glycol monomethyl ether acetate, dipropylene glycol monoethyl ether acetate, dipropylene glycol monobutyl ether acetate, dipropylene glycol diacetate, tripropylene glycol dimethyl ether, tripropylene glycol diethyl ether, tripropylene glycol dibutyl ether, tripropylene glycol monomethyl ether acetate, tripropylene glycol monoethyl ether acetate, tripropylene glycol monobutyl ether acetate, tripropylene glycol diacetate, tetrapropylene glycol dimethyl ether, tetrapropylene glycol monomethyl ether acetate, tetrapropylene glycol diacetate, butylene glycol dimethyl ether, butylene glycol monomethyl ether acetate, butylene glycol diacetate, glycerin triacetate, 3-methoxybutyl acetate, 3-methyl-3-methoxybutyl acetate, and 3-methyl-3-methoxybutyl propionate.

[0073]

Examples of the nitrogen element-containing solvents include N,N-dimethylformamide, N,N-dimethylacetamide, N,N-diethylacetamide, N-methyl-2-pyrrolidone, N-ethyl-2-pyrrolidone, N-propyl-2-pyrrolidone, 1,3-dimethyl-2-imidazolidinone, 1,3-diethyl-2-imidazolidinone, 1,3-diisopropyl-2-imidazolidinone, triethylamine, and pyridine.

[0074]

Examples of the silicone solvents include hexamethyldisiloxane, octamethyltrisiloxane, decamethyltetrasiloxane, and dodecamethylpentasiloxane.

[0075]

Moreover, in view of the solubility of the organic substance, the organic solvent is preferably a polar organic solvent. Preferably, the organic solvent includes
5 at least one selected from the group consisting of esters, ethers, ketones, alcohol-based solvents, and polyhydric alcohol derivatives, particularly preferably alcohol-based solvents, suitably ethanol or isopropyl alcohol (IPA).

[0076]

10 Here, the solvent may contain water. In this case, the water concentration is preferably 40 mass% or less, particularly 20 mass% or less or even 10 mass% or less, based on 100 mass% of the solution of the present disclosure.

15 [0077]

Moreover, a catalyst may be added to the solution of the present disclosure in order to promote the formation of an organic substance deposited film. Examples of the catalyst include acidic compounds such as
20 hexafluoroisopropanol, trifluoroacetic acid, trifluoroacetic anhydride, trifluoromethanesulfonic acid, and trifluoromethanesulfonic anhydride; and basic compounds such as pyridine, N,N-dimethyl-4-aminopyridine, ammonia, and imidazole. The amount of the catalyst added is
25 preferably 0.01 to 50 mass% based on 100 mass% of the total amount of the organic substance.

[0078]

The temperature of the solution in the immersion method, etc. is preferably 0 to 80°C. The time during
30 which the substrate is immersed in the solution is preferably at least 10 seconds but not more than 48 hours, more preferably at least 1 minute but not more than 24 hours. When the substrate is immersed in the solution, the solution may be stirred with a stirring blade or the like.

35 [0079]

Moreover, after the substrate is exposed to the solution containing the organic substance to deposit a film of the organic substance thereon, a washing step of washing the substrate with a solvent is preferably performed.

5 Examples of solvents that may be used in the washing step include the organic solvents listed above. The washing method preferably includes immersion in the solvent at 0 to 80°C for 1 to 1000 seconds. When the substrate is immersed in the solution containing the organic substance, the
10 substrate will be pulled out of the solution and washed with the solvent.

[0080]

After the washing step, preferably, inert gas such as nitrogen or argon is sprayed to the substrate to dry the
15 substrate. The temperature of the inert gas to be sprayed is preferably 0 to 80°C.

[0081]

In the selective film deposition method according to embodiments of the present disclosure in which the
20 substrate having a structure on which the first surface region and the second surface region are both exposed is exposed to the solution containing the organic substance of formula (1) and a solvent to deposit a film of the organic substance on the first surface region selectively over the
25 second surface region, when the substrate is exposed to the solution, the substrate may be exposed to a single solution as the solution to deposit a film of the organic substance on the first surface region selectively over the second surface region; or alternatively, two or more solutions may
30 be provided as the solution and the substrate may be sequentially exposed to the solutions to deposit a film of the organic substance on the first surface region selectively over the second surface region.

[0082]

35 In this case, desirably, the substrate is exposed to

the first solution, followed by washing with the solvent described above and drying, and subsequently the substrate is exposed to the second solution, also followed by washing with the solvent described above and drying. When three
5 solutions are provided as the solution, the step of washing with the solvent described above and drying is also desirably performed every time after the substrate is exposed to one solution but before the substrate is exposed to the subsequent solution. However, the washing and
10 drying step may be omitted in some cases.

[0083]

Moreover, the number of carbons of R^1 for the organic substance contained in the second or subsequent solution to which the substrate is exposed may be smaller than the
15 number of carbons of R^1 for the organic substance contained in the first solution to which the substrate is exposed. However, the aforementioned number of carbons for the organic substance contained in the second or subsequent solution to which the substrate is exposed is desirably set
20 to be greater than or equal to the aforementioned number of carbons for the organic substance contained in the first solution to which the substrate is exposed.

When the number of carbons of R^1 for the organic substance contained in the second or subsequent solution to
25 which the substrate is exposed is greater than or equal to the number of carbons of R^1 for the organic substance contained in the first solution to which the substrate is exposed, the resulting substrate may have a much higher contact angle, so that a thicker film of the organic
30 substance can be deposited selectively on the first surface region.

[0084]

In the exposure of the substrate to the solution, when two or more solutions are provided as the solution and
35 the substrate is sequentially exposed to the solutions, a

film of the organic substance can be deposited on the first surface region selectively over the second surface region even if the time during which the substrate is exposed to each solution, i.e., the time during which the substrate is immersed in each solution, is reduced.

[0085]

[Substrate after selective deposition of organic substance deposited film]

A substrate according to embodiments of the present disclosure is a substrate including a first surface region containing a metal element and a second surface region containing a nonmetal inorganic material, wherein the first surface region includes a film of the organic substance of formula (1), and the second surface region includes no film of the organic substance or a film of the organic substance on the second surface region has a thickness t_2 smaller than the thickness t_1 of the film of the organic substance on the first surface region.

The contact angle with water is preferably higher, more preferably by 10° or more, in the first surface region than in the second surface region.

[0086]

The film (deposited film) of the organic substance may be one physically adsorbed onto the first surface region or may be one chemically bound to the component contained in the substrate. The group containing a phosphorus atom, an oxygen atom, or a sulfur atom in the molecule of the organic substance described above is believed to be provided by interacting with the metal or metal oxide contained in the substrate. In this case, the film of the organic substance is believed to have a monolayer structure. The substrate surface before the deposition of the organic substance is often hydrophilic due to the metal or metal oxide contained in the substrate, while the substrate surface after the deposition of the

organic substance is often hydrophobic due to the film of the organic substance. When the organic substance used is any of the organic substances described above, the phosphorus atom, oxygen atom, or sulfur atom is believed to
5 interact with the metal or metal oxide to expose a hydrocarbon group such as an alkyl group on the surface of a film of the organic substance, and thus the deposition of the film of the organic substance is believed to make the first surface region hydrophobic.

10 Hence, when pure water is dropped on the first surface region on which the organic substance has been deposited and the angle (contact angle) between a water droplet and the wafer surface is measured by a contact angle meter, it is believed that the contact angle is
15 higher in the first surface region than in the second surface region.

EXAMPLES

[0087]

20 Hereinafter, examples that more specifically disclose embodiments of the present disclosure are described. It should be noted that the present disclosure is not limited to these examples.

[0088]

25 [Example 1]

(Preparation of solution)

Isopropyl alcohol (IPA) as a solvent and n-octadecanoic acid as an organic substance were mixed and dissolved so that the organic substance was at a
30 concentration of 1 mass%, whereby a solution containing n-octadecanoic acid and the solvent was prepared.

[0089]

(Preparation of substrate)

35 A silicon substrate having a 100 nm thick cobalt film was irradiated with UV/O₃ for 30 minutes (lamp: EUV200WS;

distance from lamp: 10 mm; UV irradiation can generate ozone from oxygen in the air) to oxidize the surface, whereby a substrate having a cobalt oxide film (CoO_x) on the surface was obtained.

5 [0090]

A silicon substrate having a 100 nm thick cobalt film was immersed in an aqueous solution of HF at a concentration of 0.5 mass% at 22°C for one minute to remove the natural oxide film from the surface, whereby a
10 substrate having a cobalt film (Co) on the surface was obtained.

[0091]

A silicon substrate having a 100 nm thick copper film was washed by UV/ O_3 irradiation (lamp: EUV200WS; distance
15 from lamp: 10 mm; UV irradiation can generate ozone from oxygen in the air) for 30 minutes, whereby a substrate having a copper oxide film (CuO_x) on the surface was obtained.

[0092]

A silicon substrate having a 100 nm thick copper film was immersed in an aqueous solution of HF at a concentration of 0.5 mass% at 22°C for one minute to remove the natural oxide film from the surface, whereby a
20 substrate having a copper film (Cu) on the surface was obtained.
25

[0093]

A silicon substrate having a 100 nm thick silicon oxide film was immersed in an aqueous solution of HF at a concentration of 0.5 mass% at 22°C for one minute, and the
30 surface was washed, whereby a substrate having a silicon oxide (SiO_x) film on the surface was obtained.

[0094]

A silicon substrate having a 30 nm thick silicon nitride film was immersed in an aqueous solution of HF at a
35 concentration of 0.5 mass% at 22°C for one minute to remove

the natural oxide film from the surface, whereby a substrate having a silicon nitride film (SiN) on the surface was obtained.

[0095]

5 A silicon substrate was immersed in an aqueous solution of HF at a concentration of 0.5 mass% at 22°C for one minute to remove the natural oxide film from the surface, whereby a substrate (Si substrate) having a silicon surface was obtained.

10 [0096]

(Surface treatment with solution containing organic substance)

The seven substrates prepared by the above treatments were each immersed in the solution described above at 22°C
15 for 24 hours for surface treatment of the substrate to deposit the organic substance on the surface of the substrate. Subsequently, the substrates were immersed in IPA 60 seconds twice, and nitrogen gas was sprayed for 60 seconds to dry the substrates.

20 [0097]

(Measurement of contact angle with water)

Pure water (about 1 μ l) was placed on the surface of each of the seven substrates according to Example 1 which had been subjected to surface treatment with the solution
25 containing the organic substance, and the angle (contact angle) between a water droplet and the wafer surface was measured by a contact angle meter (DM-301 available from Kyowa Interface Science Co., Ltd.). Table 1 shows the results.

30 [0098]

[Table 1]

	Organic substance	Organic substance concentration (mass%)	Solvent	Contact angle (°)						
				CoOx	Co	CuOx	Cu	SiOx	SiN	Si
Example 1	n-Octadecanoic acid	1	IPA	109	108	109	109	29	32	32

[0099]

As a result of the measurement of the contact angle by the above method, the CuO_x substrate, Cu substrate, CoO_x substrate, and Co substrate each had a higher contact angle than the Si substrate, SiN substrate, and SiO_x substrate, as shown in Table 1, demonstrating that the use of a carboxylic acid as an organic substance allows a film of the organic substance to be deposited selectively on a metal or metal oxide surface.

10 [0100]

[Examples 2 to 20]

The procedure was repeated as in Example 1, except that the type of the substance of the substrate surface, the type of the organic substance, the type of the solvent, the concentration (organic substance concentration) of the solution, and the like were changed as shown in Table 2, followed by evaluation. In other words, in these examples, CoO_x substrates, Co substrates, and SiO_x substrates were prepared. Table 2 shows the results.

20 [Comparative Examples 1 and 2]

In Comparative Example 1, as shown in Table 2, an IPA solution not containing any of the above-mentioned organic substances was used. In Comparative Example 2, as shown in Table 2, PGMEA as a solvent and trimethylsilyldimethylamine as an organic substance were mixed and dissolved so that the organic substance was at the concentration shown in Table 2, whereby a solution containing the organic substance and the solvent was prepared. It should be noted that trimethylsilyldimethylamine does not correspond to an organic substance of formula (1).

30 [0101]

(Preparation of substrate and Surface treatment with solution)

In Comparative Examples 1 and 2, the same substrates as in Examples 2 to 20 were prepared and subjected to

surface treatment with the respective solutions as in Examples 2 to 20.

[0102]

(Measurement of contact angle with water)

5 Pure water (about 1 μ l) was placed on the surface of each of the substrates according to Comparative Examples 1 and 2, and the angle (contact angle) between a water droplet and the wafer surface was measured by a contact angle meter (DM-301 available from Kyowa Interface Science Co., Ltd.). Table 2 shows the results.

[0103]

[Table 2]

	Organic substance	Organic substance concentration (mass%)	Solvent	Contact angle (°)		
				CoOx	Co	SiOx
Example 2	2-(Perfluorohexyl)propanoic acid	1	IPA	108	109	30
Example 3	n-Octadecylphosphonic acid	1	IPA	112	109	38
Example 4	2-(Perfluorohexyl)ethylphosphonic acid	1	IPA	109	107	39
Example 5	n-Octadecanethiol	1	IPA	110	112	45
Example 6	2-(Perfluorohexyl)ethanethiol	1	IPA	101	102	31
Example 7	n-Octadecanoic acid	1	EtOH	106	106	68
Example 8	n-Octadecylphosphonic acid	1	EtOH	112	110	35
Example 9	n-Octadecanethiol	1	EtOH	111	109	42
Example 10	n-Octadecanoic acid	0.1	PGMEA	102	102	60
Example 11	n-Octadecylphosphonic acid	0.1	PGMEA	105	106	35
Example 12	n-Octadecanethiol	0.1	PGMEA	106	107	41
Example 13	n-Octadecanoic acid	0.1	IPA	101	101	28
Example 14	n-Octadecanoic acid	10	IPA	112	112	31
Example 15	n-Octadecanoic acid	1	THF	100	101	32
Example 16	n-Octadecylphosphonic acid	1	THF	109	109	35
Example 17	n-Octadecanethiol	1	THF	106	107	42
Example 18	n-Octadecanoic acid	1	EtOAc	102	101	30
Example 19	n-Octadecylphosphonic acid	0.1	EtOAc	110	111	35
Example 20	n-Octadecanethiol	1	EtOAc	108	108	40
Comparative Example 1	None	0	IPA	74	71	35
Comparative Example 2	Trimethylsilyldimethylamine	1	PGMEA	75	73	101

Note) EtOH: ethanol; PGMEA: propylene glycol 1-monomethyl ether 2-acetate; THF: tetrahydrofuran; EtOAc: ethyl acetate

[0104]

As is clear from the results in Table 2, in each of

Examples 2 to 20, the Co substrate or CoO_x substrate had a higher contact angle than the SiO_x substrate, demonstrating that the use of an organic substance of formula (1) as an organic substance allows a film of the organic substance to be deposited selectively on a metal or metal oxide surface.

In contrast, in each of Comparative Examples 1 and 2 in which no or another organic substance was used, the contact angles of the Co substrate and CoO_x substrate did not increase. In particular, in Comparative Example 2, the SiO_x substrate had a higher contact angle than the CoO_x substrate and Co substrate, and it is considered that trimethylsilyldimethylamine was deposited selectively on the SiO_x substrate.

[0105]

(Elemental composition analysis by x-ray photoelectron spectroscopy (XPS) on substrates obtained in Examples)

Of the examples described above, the substrates obtained in the examples with the numbers shown in Table 3 below were subjected to analysis of the elemental composition of the substrate surface by x-ray photoelectron spectroscopy (XPS). Table 3 shows the results.

[0106]

[Table 3]

	Organic substance	Organic substance concentration (mass%)	Solvent	Surface elemental composition		
				CoO _x	Co	SiO _x
Example 3	n-Octadecylphosphonic acid	1	IPA	P	P	-
Example 4	2-(Perfluorohexyl)ethylphosphonic acid	1	IPA	P	P	-
Example 5	n-Octadecanethiol	1	IPA	S	S	-
Example 6	2-(perfluorohexyl)ethanethiol	1	IPA	S	S	-
Example 8	n-Octadecylphosphonic acid	1	EtOH	P	P	-
Example 9	n-Octadecanethiol	1	EtOH	S	S	-
Example 11	n-Octadecylphosphonic acid	0.1	PGMEA	P	P	-
Example 12	n-Octadecanethiol	0.1	PGMEA	S	S	-
Example 16	n-Octadecylphosphonic acid	1	THF	P	P	-
Example 17	n-Octadecanethiol	1	THF	S	S	-
Example 19	n-Octadecylphosphonic acid	0.1	EtOAc	P	P	-
Example 20	n-Octadecanethiol	1	EtOAc	S	S	-

Note) EtOH: ethanol; PGMEA: propylene glycol 1-monomethyl ether 2-acetate; THF: tetrahydrofuran; EtOAc: ethyl acetate

[0107]

As is clear from the results in Table 3, the surface of the Co substrate or CoO_x substrate obtained in each of the examples shown in Table 3 was found to exhibit an intense peak of the characteristic element contained in the organic substance used, i.e., a P element in the case of the phosphonic acids, or a S element in the case of the thiols. In contrast, no peaks of a P element, a S element, etc. were observed on the surface of the SiO_x substrate.

Thus, it is believed that a phosphonic acid or thiol film was formed on the Co substrate and CoO_x substrate.

[0108]

[Examples 21 to 27]

(Evaluation of heat resistance)

The same procedure as in Example 1 was followed using the organic substance shown in Table 4 to form a film of the organic substance on the surface of a CoO_x film. The thus prepared substrate was set in a quartz tube, which was then evacuated in vacuo for one hour using an oil pump and then heated to heat the substrate.

The heating was stopped after one hour from the time when the temperature of the substrate reached a predetermined temperature. After cooling for 30 minutes, the substrate was taken out. The substrate after heating was measured for contact angle with water as described above in "Measurement of contact angle with water". The heating temperature was increased from 100°C by an increment of 50°C , and the highest heating temperature at which heating decreases the contact angle by 10° or less was regarded as the heat resistance temperature. Here, if the highest heating temperature (heat resistance temperature) was 100°C , this means that the difference between the contact angle of the substrate before heating and the contact angle of the substrate heated at 100°C was 10°C or less, but heating at 150°C decreased the contact angle by more than 10°C .

[0109]

[Table 4]

	Organic substance	Organic substance concentration (mass%)	Solvent	Heat resistance temperature (°C)
Example 21	n-Octadecanoic acid	1	IPA	150
Example 22	n-Nonanoic acid	1	IPA	100
Example 23	2-(Perfluorohexyl)propanoic acid	1	IPA	150
Example 24	n-Octadecylphosphonic acid	1	IPA	250
Example 25	2-(Perfluorohexyl)ethylphosphonic acid	1	IPA	300
Example 26	n-Octadecanethiol	1	IPA	150
Example 27	2-(Perfluorohexyl)ethanethiol	1	IPA	200

[0110]

5 As is clear from Table 4, each of the organic substances used in Examples 21 to 27, after being deposited on the substrate, was found to be less likely to disappear from the substrate due to degradation, desorption, etc., even when heated, and to have excellent heat resistance.

10 It was found that, among these organic substances, the substrates on which n-octadecylphosphonic acid used in Example 24 or 2-(perfluorohexyl)ethylphosphonic acid used in Example 25 was deposited had particularly excellent heat resistance, and the organic substances deposited on the

15 substrates had particularly high heat resistance because they did not disappear due to degradation but remained on the substrates, even when heated to 250°C or higher.

[0111]

Moreover, a comparison between Examples 22 and 23

20 shows that while carboxylic acids of the same number of carbons were used, Example 23 using 2-(perfluorohexyl)propanoic acid in which hydrogen atoms have been replaced with fluorine atoms exhibited higher heat resistance. Similarly, comparisons between Examples 24 and

25 25 and between Examples 26 and 27 show that the heat resistance was also increased by replacing hydrogen atoms with fluorine atoms in a phosphonic acid or thiol.

[0112]

[Example 28]

(Preparation of solution)

Ethanol (EtOH) as a solvent and n-octadecylphosphonic acid as an organic substance were mixed and dissolved so that the organic substance was at a concentration of 1 mass%,
5 whereby a solution A was prepared. Moreover, ethanol (EtOH) as a solvent and n-octadecanethiol as an organic substance were mixed and dissolved so that the organic substance was at a concentration of 1 mass%, whereby a solution B was prepared.

10 (Surface treatment with solution containing organic substance)

A CoO_x-containing substrate, a Co-containing substrate, and a SiO_x-containing substrate each prepared as described above in "Preparation of substrate" were each
15 immersed in the solution A at 22°C for 0.5 hours and subsequently immersed in IPA for 60 seconds twice. Further, each substrate was immersed in the solution B at 22°C for 0.5 hours for surface treatment of the substrate to deposit the organic substance on the surface of the
20 substrate. Subsequently, each substrate was immersed in IPA for 60 seconds twice, and nitrogen gas was sprayed for 60 seconds to dry the substrate.

[0113]

[Examples 29 to 31]

25 The procedure was repeated as in Example 28, except that the type of the organic substance, the types of the solutions A and B, and the immersion times of the solutions A and B were changed as shown in Table 5, followed by evaluation.

30 [0114]

(Measurement of contact angle with water)

Pure water (about 1 μ l) was placed on the surface of each of the substrates according to Examples 28 to 31, and the angle (contact angle) between a water droplet and the
35 wafer surface was measured by a contact angle meter (DM-301

available from Kyowa Interface Science Co., Ltd.). Table 5 shows the results together with the results of Example 3.

[0115]

[Table 5]

	Solution A				Solvent B				Immersion time (hr)		Contact angle (°)		
	Organic substance	Number of carbons of organic substance	Organic substance concentration (mass%)	Solvent	Organic substance	Number of carbons of organic substance	Organic substance concentration (mass%)	Solvent	Solution A	Solution B	CoOx	Co	SiOx
Example 3	n-Octadecylphosphonic acid	18	1	IPA	-	-	-	-	24	-	112	109	38
Example 28	n-Octadecylphosphonic acid	18	1	EtOH	n-Octadecanethiol	18	1	EtOH	0.5	0.5	109	109	34
Example 29	n-Octadecylphosphonic acid	18	1	EtOH	n-Octadecanethiol	18	1	EtOH	0.8	0.2	108	108	30
Example 30	n-Octadecanethiol	18	1	EtOH	n-Octadecylphosphonic acid	18	1	EtOH	0.5	0.5	108	108	31
Example 31	n-Octadecylphosphonic acid	18	1	EtOH	n-Dodecanethiol	12	1	EtOH	0.5	0.5	106	106	30

[0116]

As is clear from the results in Table 5, in each of Examples 28 to 31, the Co-containing substrate and the CoO_x-containing substrate each had a higher contact angle than the SiO_x-containing substrate, demonstrating that the use of two solutions each containing an organic substance of formula (1) as organic substances allows films of the organic substances to be deposited selectively on a metal or metal oxide surface.

10 [0117]

Moreover, comparisons between Example 3 and Examples 28 to 31 show that when treated with the two solutions each containing an organic substance for a short time of one hour, the Co-containing substrates and CoO_x-containing substrates each had a contact angle substantially as high as that in Example 3. Moreover, a comparison between Example 28 and Example 31 shows that the contact angle increased when the number of carbons of the organic substance in the solution B was higher compared to the number of carbons of the organic substance in the solution A.

[0118]

[Example 32]

(Preparation of solution)

25 Ethanol (EtOH) as a solvent and (10-phenyldecyl)phosphonic acid as an organic substance were mixed and dissolved so that the organic substance was at a concentration of 1 mass%, whereby a solution was prepared. (Surface treatment with solution containing organic substance)

30 A CoO_x-containing substrate, a Co-containing substrate, and a SiO_x-containing substrate each prepared as described above in "Preparation of substrate" were each immersed in the solution at 22°C for one hour for surface treatment of the substrate to deposit the organic substance

on the surface of the substrate. Subsequently, each substrate was immersed in IPA for 60 seconds twice, and nitrogen gas was sprayed for 60 seconds to dry the substrate.

5 [0119]

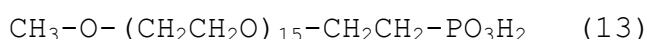
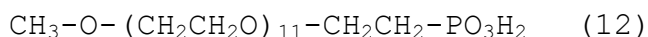
(Measurement of contact angle with water)

Pure water (about 1 μ l) was placed on the surface of each of the substrates according to Example 32, and the angle (contact angle) between a water droplet and the wafer surface was measured by a contact angle meter (DM-301 available from Kyowa Interface Science Co., Ltd.). Table 6 shows the results together with the results of Example 3.

10 [0120]

[Examples 33 and 34]

15 The procedure was repeated as in Example 32, except that polyethylene glycol methyl ether phosphonic acid-15 represented by the following formula (12) or polyethylene glycol methyl ether phosphonic acid-11 represented by the following formula (13) was used as the organic substance, followed by evaluation. Table 6 shows the results.



20 [0121]

[Table 6]

	Organic substance	Organic substance concentration (mass%)	Solvent	Immersion time (hr)	Contact angle (°)		
					CoOx	Co	SiOx
Example 3	n-Octadecylphosphonic acid	1	IPA	24	112	109	38
Example 32	(10-Phenyldecyl)phosphonic acid	1	EtOH	1	90	91	40
Example 33	Polyethylene glycol methyl ether phosphonic acid -15	1	EtOH	1	41	40	18
25 Example 34	Polyethylene glycol methyl ether phosphonic acid -11	1	EtOH	1	45	43	20

[0122]

As is clear from the results in Table 6, in each of Examples 32 to 34, the Co-containing substrate and the CoO_x-containing substrate each had a higher contact angle than the SiO_x-containing substrate, demonstrating that the use of an organic substance of formula (10) or (11) as an

30

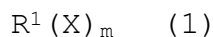
organic substance allows a film of the organic substance to be deposited selectively on a metal or metal oxide surface. [0123]

5 The present application claims priority under the Paris Convention and the law of the designated state to Japanese Patent Application No. 2021-014552 filed on February 1, 2021, the entire contents of which are hereby incorporated by reference.

CLAIMS

Claim 1. A selective film deposition method,
comprising:

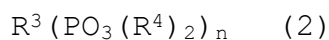
5 exposing a substrate having a structure on which a
first surface region containing a metal element and a
second surface region containing a nonmetal inorganic
material are both exposed, to a solution containing an
organic substance represented by formula (1) shown below
10 and a solvent to deposit a film of the organic substance on
the first surface region selectively over the second
surface region:



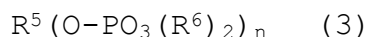
wherein R^1 is a C4-C100 hydrocarbon group optionally
15 containing a heteroatom or a halogen atom, and m hydrogen
atoms of the hydrocarbon group are replaced with X; X is -
 $PO_3(R^2)_2$, $-O-PO_3(R^2)_2$, $-CO_2R^2$, $-SR^2$, or $-SSR^1$; each R^2 is a
hydrogen atom or a C1-C6 alkyl group; and m is a positive
integer, and m/r is 0.01 to 0.25 where r is the number of
20 carbons of the hydrocarbon group.

Claim 2. The selective film deposition method
according to claim 1,

wherein the organic substance of formula (1)
25 comprises at least one organic substance represented by at
least one selected from the group consisting of the
following formulas (2) to (5):



wherein R^3 is a C4-C100 hydrocarbon group optionally
30 containing a heteroatom or a halogen atom, and n hydrogen
atoms of the hydrocarbon group are replaced with $(PO_3(R^4)_2)$;
n is 1 or 2; R^4 is a hydrogen atom or a C1-C6 alkyl group;
and each R^4 may be the same or different;



35 wherein R^5 is a C4-C100 hydrocarbon group optionally

containing a heteroatom or a halogen atom, and n hydrogen atoms of the hydrocarbon group are replaced with (O-PO₃(R⁶)₂); n is 1 or 2; R⁶ is a hydrogen atom or a C1-C6 alkyl group; and each R⁶ may be the same or different;

5 R⁷(CO₂R⁸)_n (4)

wherein R⁷ is a C4-C100 hydrocarbon group optionally containing a heteroatom or a halogen atom, and n hydrogen atoms of the hydrocarbon group are replaced with (CO₂R⁸); n is 1 or 2; R⁸ is a hydrogen atom or a C1-C6 alkyl group; and each R⁸ may be the same or different; and

10 R⁹(SR¹⁰)_n (5)

wherein R⁹ is a C4-C100 hydrocarbon group optionally containing a heteroatom or a halogen atom, and n hydrogen atoms of the hydrocarbon group are replaced with (SR¹⁰); n is 1 or 2; R¹⁰ is a hydrogen atom, a C1-C6 alkyl group, or -S-R⁹; and each R¹⁰ may be the same or different.

Claim 3. The selective film deposition method according to claim 1 or 2,

20 wherein the substrate is exposed to the solution to obtain a substrate in which a contact angle with water is higher in the first surface region than in the second surface region.

25 Claim 4. The selective film deposition method according to claim 3,

wherein a substrate is obtained in which a contact angle with water is higher by at least 10° in the first surface region than in the second surface region.

30

Claim 5. The selective film deposition method according to claim 2,

wherein R⁴, R⁶, R⁸, and R¹⁰ in formulas (2) to (5) are hydrogen atoms.

35

Claim 6. The selective film deposition method according to any one of claims 1 to 5,

wherein the metal element is contained in the form of a metal or a metal oxide, and

5 the metal is at least one selected from the group consisting of Cu, Co, Ru, Ni, Pt, Al, Ta, Ti, and Hf, and the metal oxide is at least one oxide of at least one metal selected from the group consisting of Cu, Co, Ru, Ni, Pt, Al, Ta, Ti, and Hf.

10

Claim 7. The selective film deposition method according to any one of claims 1 to 6,

wherein the nonmetal inorganic material is at least one selected from the group consisting of silicon, silicon oxide, silicon nitride, and silicon oxynitride.

15

Claim 8. The selective film deposition method according to any one of claims 1 to 7,

20 wherein a concentration of the organic substance of formula (1) in the solution is at least 0.01 mass% but not more than 20 mass% based on 100 mass% of a total amount of the solution.

Claim 9. The selective film deposition method according to any one of claims 1 to 8,

25

wherein the solvent is an organic solvent.

Claim 10. The selective film deposition method according to claim 9,

30 wherein the organic solvent comprises at least one selected from the group consisting of esters, ethers, ketones, alcohol-based solvents, and polyhydric alcohol derivatives.

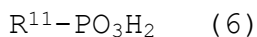
35 Claim 11. The selective film deposition method

according to claim 10,

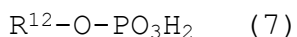
wherein the organic solvent comprises ethanol or isopropyl alcohol.

5 Claim 12. The selective film deposition method according to any one of claims 1 to 11,

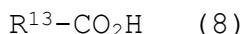
 wherein the organic substance of formula (1) comprises at least one organic substance represented by at least one selected from the group consisting of the
10 following formulas (6) to (9):



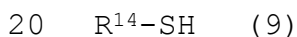
wherein R^{11} is a C6-C100 monovalent hydrocarbon group optionally containing a heteroatom or a halogen atom;



15 wherein R^{12} is a C6-C100 monovalent hydrocarbon group optionally containing a heteroatom or a halogen atom;



wherein R^{13} is a C6-C100 monovalent hydrocarbon group optionally containing a heteroatom or a halogen atom; and



wherein R^{14} is a C6-C100 monovalent hydrocarbon group optionally containing a heteroatom or a halogen atom.

 Claim 13. The selective film deposition method
25 according to claim 12,

 wherein the organic substance of formula (1) comprises at least one organic substance represented by at least one selected from the group consisting of formula (6) and formula (7).

30

 Claim 14. The selective film deposition method according to claim 12,

 wherein the organic substance of formula (1) comprises an organic substance of formula (8).

35

Claim 15. The selective film deposition method according to claim 12,

wherein the organic substance of formula (1) comprises an organic substance of formula (9).

5

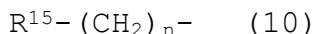
Claim 16. The selective film deposition method according to any one of claims 12 to 15,

wherein R^{11} , R^{12} , R^{13} , and R^{14} are each a hydrocarbon group whose hydrogen atoms are partially or fully replaced with fluorine atoms.

10

Claim 17. The selective film deposition method according to any one of claims 12 to 15,

wherein R^{11} , R^{12} , R^{13} , and R^{14} are each a monovalent organic group represented by the following formula (10):

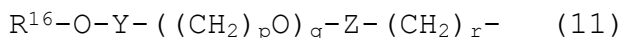


wherein R^{15} is a hydrogen atom or a monovalent hydrocarbon group optionally containing a heteroatom or a halogen atom; and n is an integer of 2 to 20, and the total number of carbons in formula (10) is 6 to 100.

20

Claim 18. The selective film deposition method according to any one of claims 12 to 15,

wherein R^{11} , R^{12} , R^{13} , and R^{14} are each a monovalent organic group represented by the following formula (11):



wherein R^{16} is a hydrogen atom, a methyl group, or a phenyl group; Y and Z are each any divalent group or a direct bond; p is an integer of 1 to 4, and q and r are positive integers; the total number of carbons in formula (11) is 6 to 100; and the repeating units $(CH_2)_pO$ and CH_2 may be present in any order in the formula.

30

Claim 19. The selective film deposition method according to any one of claims 1 to 18,

35

wherein the substrate is washed with a solvent after the film of the organic substance of formula (1) is selectively deposited on the substrate.

5 Claim 20. The selective film deposition method according to any one of claims 1 to 19,

 wherein two or more solutions are provided as the solution, and the substrate is sequentially exposed to the solutions.

10

 Claim 21. The selective film deposition method according to claim 20,

 wherein the number of carbons of R^1 for the organic substance in the second or subsequent solution to which the substrate is exposed is greater than or equal to the number of carbons of R^1 for the organic substance in the first solution to which the substrate is exposed.

15

 Claim 22. A solution for use in the selective film deposition method according to any one of claims 1 to 21, comprising:

20

 an organic substance represented by the following formula (1); and a solvent:



25 wherein R^1 is a C4-C100 hydrocarbon group optionally containing a heteroatom or a halogen atom, and m hydrogen atoms of the hydrocarbon group are replaced with X; X is - $PO_3(R^2)_2$, -O- $PO_3(R^2)_2$, - CO_2R^2 , - SR^2 , or - SSR^1 ; each R^2 is a hydrogen atom or a C1-C6 alkyl group; and m is a positive integer, and m/r is 0.01 to 0.25 where r is the number of carbons of the hydrocarbon group.

30

 Claim 23. The solution according to claim 22, wherein the solvent comprises ethanol or isopropyl alcohol, and a concentration of the organic substance of

35

formula (1) is at least 0.01 mass% but not more than 20 mass% based on 100 mass% of a total amount of the solution.

Claim 24. A substrate, comprising:

5 a first surface region containing a metal element;
and a second surface region containing a nonmetal inorganic material,

wherein the first surface region comprises a film of an organic substance represented by formula (1) shown
10 below, and the second surface region comprises no film of the organic substance or a film of the organic substance on the second surface region has a thickness t_2 smaller than a thickness t_1 of the film of the organic substance on the first surface region:

15 $R^1(X)_m$ (1)

wherein R^1 is a C4-C100 hydrocarbon group optionally containing a heteroatom or a halogen atom, and m hydrogen atoms of the hydrocarbon group are replaced with X; X is - $PO_3(R^2)_2$, -O- $PO_3(R^2)_2$, -CO₂R², -SR², or -SSR¹; each R² is a
20 hydrogen atom or a C1-C6 alkyl group; and m is a positive integer, and m/r is 0.01 to 0.25 where r is the number of carbons of the hydrocarbon group.

Claim 25. The substrate according to claim 24,

25 wherein a contact angle with water is higher in the first surface region than in the second surface region.

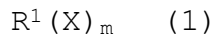
Claim 26. The substrate according to claim 25,

wherein the contact angle with water is higher by at least 10° in the first surface region than in the second surface region.
30

Claim 27. An organic substance deposited film, formed by the selective film deposition method according to any

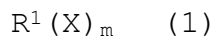
35 one of claims 1 to 21,

wherein the deposited film comprises an organic substance represented by the following formula (1) deposited on a substrate:



5 wherein R^1 is a C4-C100 hydrocarbon group optionally containing a heteroatom or a halogen atom, and m hydrogen atoms of the hydrocarbon group are replaced with X; X is - $PO_3(R^2)_2$, -O- $PO_3(R^2)_2$, -CO₂R², -SR², or -SSR¹; each R² is a hydrogen atom or a C1-C6 alkyl group; and m is a positive
10 integer, and m/r is 0.01 to 0.25 where r is the number of carbons of the hydrocarbon group.

Claim 28. An organic substance, represented by the following formula (1) for use in the selective film
15 deposition method according to any one of claims 1 to 21:



wherein R^1 is a C4-C100 hydrocarbon group optionally containing a heteroatom or a halogen atom, and m hydrogen atoms of the hydrocarbon group are replaced with X; X is -
20 $PO_3(R^2)_2$, -O- $PO_3(R^2)_2$, -CO₂R², -SR², or -SSR¹; each R² is a hydrogen atom or a C1-C6 alkyl group; and m is a positive integer, and m/r is 0.01 to 0.25 where r is the number of carbons of the hydrocarbon group.